

4

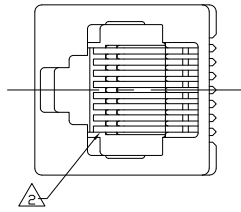
3

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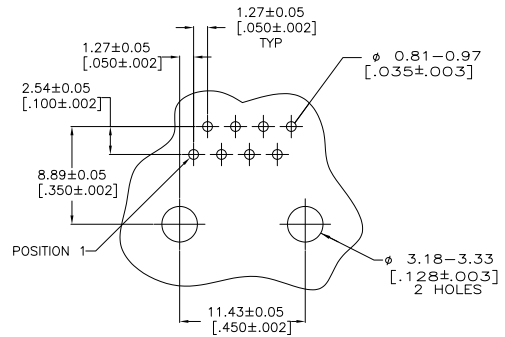
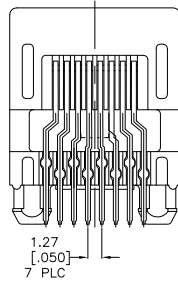
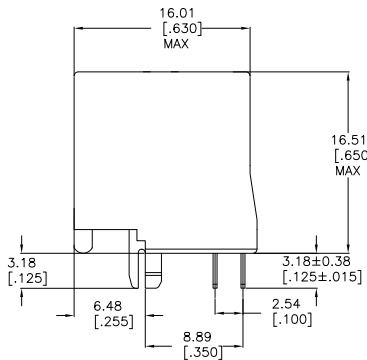
LOC		DIST		REVISIONS		
F	LNK	DESCRIPTION	DATE	BY	APPD	
AA	00					
B		ECO-07-017784	14AUG07	LAM	PR	



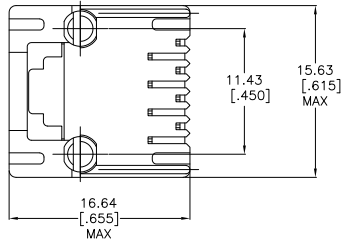
- MATERIAL: HOUSING - HTN MOLDING COMPOUND, UL 94V-0 COLOR: BLACK
 TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27 μ m [.000050] MIN THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA, 3.81 μ m [.000150] MIN THICK MATTE TIN IN SOLDER AREA AND 1.27 μ m [.000050] MIN THICK NICKEL UNDERPLATE

\triangle CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81 PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

- BULK PACKAGED IN A TRAY.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 COMPONENT SIDE



THIS DRAWING IS A CONTROLLED DOCUMENT.		DRN L. MAYER	ORJAN2005	Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		CHK S. REEDCE	14AUG2007	NAME S. FLICKINGER	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		ZPFC 14AUG2007		MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS	
0 PLC ± -		PRODUCT SPEC 108-1163		RESTRICTED TO	
1 PLC ± -		APPLICATION SPEC 114-2048		SIZE CASE CODE DRAWING NO	
2 PLC ± 0.1%(.005)		MATERIAL SEE NOTE 1		A2 00779 C=5569284	
3 PLC ± -		FINISH SEE NOTE 1		SCALE 4:1 SHEET 1 of 1 REV B	
4 PLC ± -		CUSTOMER DRAWING			
ANGLES ± -					